

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BTN9970LV	**Issued**	22. April 2022
MA#	MA005713524		
Package	PG-HSOF-7-1	**Weight***	345.68 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.768	0.22	0.22	2223	2223
chip_2	inorganic material	silicon	7440-21-3	0.388	0.11	0.11	1121	1121
chip_3	inorganic material	silicon	7440-21-3	0.628	0.18	0.18	1817	1817
leadframe	inorganic material	phosphorus	7723-14-0	0.055	0.02		158	
	non noble metal	iron	7439-89-6	0.182	0.05		526	
	non noble metal	copper	7440-50-8	181.611	52.53	52.60	525378	526062
wire	non noble metal	copper	7440-50-8	0.157	0.05	0.05	455	455
encapsulation	inorganic material	zincoxide	1314-13-2	1.528	0.44		4420	
	miscellaneous	miscellaneous	-	6.112	1.77		17680	
	plastics	epoxy resin	-	22.918	6.63		66300	
	inorganic material	silicondioxide	60676-86-0	122.232	35.36	44.20	353601	442001
leadfinish	non noble metal	tin	7440-31-5	2.025	0.59	0.59	5858	5858
plating	noble metal	silver	7440-22-4	0.271	0.08	0.08	785	785
solder	non noble metal	tin	7440-31-5	0.024	0.01		68	
	noble metal	silver	7440-22-4	0.029	0.01		85	
	non noble metal	lead	7439-92-1	1.127	0.33	0.35	3260	3413
glue	plastics	Polyimide	26023-21-2	0.178	0.05	0.05	515	515
heat sink clip	inorganic material	phosphorus	7723-14-0	0.002			5	
	non noble metal	iron	7439-89-6	0.005			16	
	non noble metal	copper	7440-50-8	5.437	1.57	1.57	15729	15750
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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